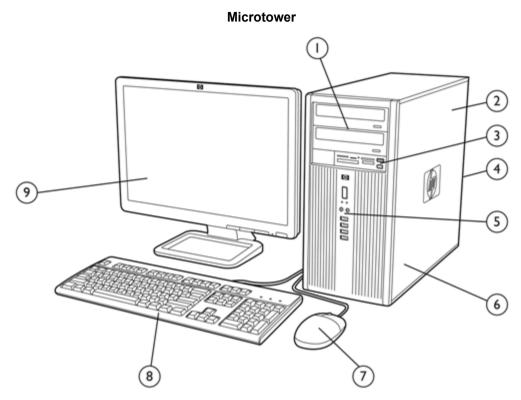
Overview

Windows®. Life without Walls™. HP recommends Windows.

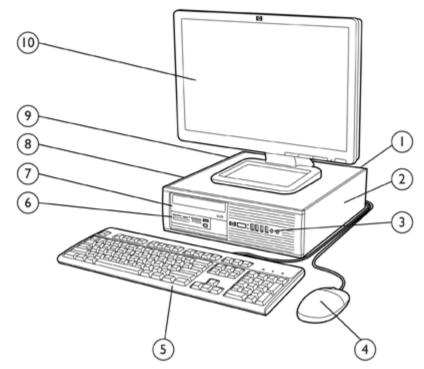


- (2) 5.25" external optical disk drive bays
 (2) 3.5" internal hard disk drive bays
- 320-watt standard efficiency power supply, Active Power 6. Factor Correction (PFC) Optional: 89% efficient energy saving power supply
- 3. (1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device
- Rear I/O: (6) USB 2.0, (1) standard serial port, (1) optional serial port, (1) optional parallel port, (2) PS/2, (1) RJ-45, (1) VGA, (1) audio in, (1) audio out, (1) Display Port
- 5. Front I/O: (4) USB 2.0, headphone and microphone, Dual Color Diagnostic LEDs
- (1) full-height PCI slot, (2) full-height PCIe x1 slots, (1) full-height PCIe x16 slot
- 7. HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser Mouse
- 8. HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard Keyboard
 - 9. HP monitor (sold separately)



Overview

Small Form Factor



- Rear I/O: (6) USB 2.0, (1) standard serial port, (1)
 optional serial port, (1) optional parallel port, (2) PS/2, (1)
 RJ-45, (1) VGA, audio in/out, (1) DisplayPort
- 2. (1) low profile PCI slot, (2) low profile PCIe x1 slots,
 (1) low profile PCIe x16 slot
- Front I/O: (4) USB 2.0, headphone and microphone, Dual 8. Color Diagnostic LEDs
- 4. HP Optical Scroll Mouse (PS/2 or USB), or HP USB Laser Mouse
- 5. HP Standard Keyboard (PS/2 or USB) or HP USB Smartcard Keyboard

- (1) 3.5" external bay for optional HP 22-in-1 Media Card Reader, pocket media drive, or other 3.5" device
- (1) 5.25" external bay for optional optical drive, or other 5.25" device (bay tilts up for device removal and insertion)
- (1) 3.5-inch internal drive bay supporting primary hard disk drive
- 240-watt power supply Optional: 89% efficient energy saving power supply
 HP Monitor (sold separatoly)
- 10. HP Monitor (sold separately)

At A Glance

 The HP Compaq 6005 Pro Business PC is a high performance PC with energy efficient features designed to exceed expectations and deliver results without compromise

7.

- AMD 785G chipset with integrated ATI Radeon HD 4200 graphics supporting DirectX 10.1
- Side Port Memory for increased power savings and increased graphics performance
- Standard dual display support (DisplayPort and VGA)
- AMD Phenom[™] II Quad-Core, Triple-Core, and Dual-Core processors; AMD Athlon[™] II Dual-Core processors; AMD Sempron[™] processor; all processors with AMD-V support
- Embedded TPM1.2 compliant security module* (Vista Bit-Locker ready)
- Support for up to 500-GB SATA 3.0Gb/s Smart IV hard drives
- Value-added software on select models
 - HP Support Assistant
 - O HP Software Agent
 - O McAfee Anti-Virus with 60 day Live Update Subscription
 - HP Vision Diagnostics software
 - Microsoft Office 2007
 - O PDF Complete
 - O Computrace Enabler for Desktops (select countries)
 - HP System Software manager
 - O HP Power Manager
 - O Firefox- HP Virtual Browser



Overview

- Value-added software available for free download from the Web (http://www.hp.com/go/easydeploy)
 - HP Client Automation Starter Edition
 - O HP Client Manager for Altiris
 - O HP SoftPaq Download Manager
 - O HP System Software Manager
 - HP Client Catalog for Microsoft SMS
- Fully compatible software OS image across all models (Microtower, Small Form Factor)
- HP BIOS for security, manageability and software image stability
- Protected by HP Services, including standard warranties up to 5-5-5 (terms and conditions vary by country; certain restrictions and exclusions apply)
- Selected configurations with global availability easily set up and ordered through HP.com Business to Business portals (http://h10019.www1.hp.com/business-site/index.html)
- Tailored HP Factory Express deployment and lifecycle services available (http://h71028.www7.hp.com/enterprise/cache/97688-0-0-225-121.aspx)

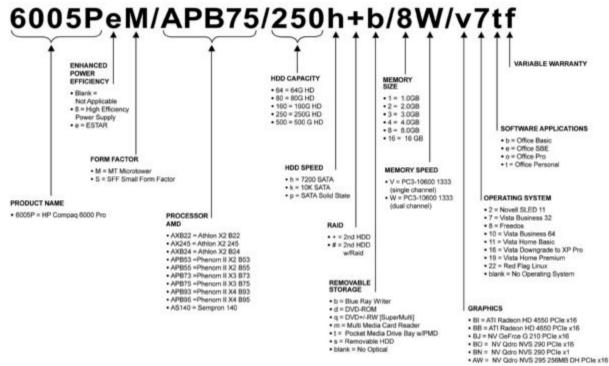
*TPM module disabled where use is restricted by law; for example, Russia.



Configurable Components - Select Models (localized by Regions)

Model Key and Example

NOTE: This diagram is an example that illustrates how to read the model number. It is not intended to give every available configuration choice specified in the body of this document and may include references to features that are out of date and no longer available. Because the configurations offered vary by region, some features listed may not be available in all countries.





Standard Features and Configurable Components (availability may vary by country)

Operating System - One of the following	Preinstalled	Genuine Windows 7 Professional Edition 32* Genuine Windows 7 Professional Edition 64* Windows XP Professional (available through downgrade rights from Genuine Windows 7 Professional)** Genuine Windows 7 Home Premium Edition 32* Genuine Windows 7 Home Premium Edition 64* Genuine Windows 7 Home Basic Edition 32* Genuine Windows Vista Business 32** Genuine Windows Vista Home Basic 32** Windows XP Professional (available through downgrade rights from Genuine Windows Vista Business)***+ Novell SUSE Linux Enterprise Desktop 11† FreeDOS
	Supported	Genuine Windows Vista Business 64**
		Genuine Windows Vista Enterprise 32**
		Genuine Windows Vista Enterprise 64**
	Certified	Novell SUSE Linux Enterprise Desktop 11 ⁺
		Red Hat Enterprise Linux ⁺⁺
		de, available as a separate download for Windows 7 Professional, works are such as Windows Virtual PC to run older Windows XP business s 7 desktop.
	purchased hardware and of Windows 7 functional	
	See http://www.microsol	ft.com/windows/windows-7/ for details.
	http://www.microsoft.com	a product features require advanced or additional hardware. See: n/windowsvista/getready/hardwarereqs.mspx and:

http://www.microsoft.com/windowsvista/getready/nardwarereqs.mspx and. http://www.microsoft.com/windowsvista/getready/capable.mspx for details. Windows Vista Upgrade Advisor can help you determine which features of Windows Vista will run on your computer. To download the tool, visit: http://www.windowsvista.com/upgradeadvisor.

+ Windows 7 Professional disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.

++ Windows Vista Business disk may also be included for future upgrade if desired. To qualify for this downgrade an end user must be a business (including governmental or educational institutions) and is expected to order annually at least 25 customer systems with the same custom image.

† The following features are not supported by Novell SUSE Linux Enterprise Desktop:

- HP 22-in-1 Media Card Reader with PCI Card
- HP ProtectTools

•

- SATA Blu-ray Writer playback of commercial movies
- Broadcom NetXtreme Gigabit Ethernet PCIe NIC Plus Card
- 2nd serial port adapter (including low profile)
- Power Management features (US ENERGY STAR)

†† The following features are not supported by Red Hat Enterprise Linux:

- HP 22-in-1 Media Card Reader with PCI Card
- Integrated 1.2 TPM Embedded Security Chip
- Broadcom NetXtreme Gigabit Ethernet PCIe NIC Plus Card
- LSI PCEe x1 Hi-Speed 56K International SoftModem
- HP FireWire / IEEE 1394 PCI Card (full height and low profile)



Standard Features a	and Configurable Components (availal	bility may vary by country)			
	 2nd serial port adapter (including low profile HP Wireless 802.11b/g/n PCIe x1 Card HP USB Smartcard Keyboard 				
	Power Management features (US ENERG	Y STAR)			
Value-added Software	HP Software Agent	Microsoft Office 2007 Basic			
(on select models; not	HP Support Assistant	Microsoft Office 2007 Personal			
included with FreeDOS)	HP Systems Software Manager	Microsoft Office 2007 Professional			
	HP Vision Diagnostics	Microsoft Office 2007 Small Business Edition			
	HP Power Manager	Integrated DASH 1.1 Manageability			
	HP Backup and Recovery Manager (only with	Microsoft Internet Explorer			
	Windows custom downgrade to Windows XP)	PDF Complete			
	McAfee Total Protection Anti-Virus with 60 day trial Subscription	Computrace Enabler for Desktops (select countries)*			
	Roxio Creater Business (select models)	HP Skyroom (trial version)			
	Firefox-HP Virtual Browser	Corel WinDVD (select models)			
	SRS Premium Sound Software for HP Thin USB Powered Speakers (select models)				
	* Requires HP LoJack Pro for ProtectTools for fu sold separately.	ull functionality. Tracking and tracing subscription			
	HP Client Automation – Starter Edition	HP Client Catalog for Microsoft SMS			
(available for free download from the Web	HP Client Manager from Symantec	HP Systems Software Manager			
http://www.hp.com/go/ easydeploy)	HP SoftPaq Download Manager	HP Disk Sanitizer, External Edition			
Value-added Services and Features	HP Stable Platform Program	Factory Express Deployment and Lifecycle Services			
	Business-to-Business Portals	TPM 1.2 Security chip*			
	HP Global Series Services				
	* TPM module disabled where use is restricted I	by law; for example, Russia.			
Service and Support	and on-site repair for terms up to 5 years. Respo	ntries/regions do not offer one year onsite and w.hp.com/go/lookuptool. Intry. Certain restrictions and exclusions apply. ant to a service contract between HP and an ailable in certain countries. Global service onable best effort and may vary by country. Inly to HP-configured, HP and HP-qualified, third-			



Standard Features and Configurable Components (availability may vary by country)

	Microtower	Small Form Factor
Chassis Dimensions	14.85 x 6.95 x 16.96 in	3.95 x 13.30 x 14.90 in
(H x W x D)	377.2 x 176.5 x 430.8 mm	100.3 x 337.8 x 378.5
Optional Tower Stand	N/A	1.05 x 6.95 x 7.83 in
Dimensions (H x W x D)		(26.75 x 176.46 x 198.87 mm)
System weight*	20.5 lb (9.3 kg)	16.0 lb (7.26 kg)
System volume	1739 cu in	941.63 cu in
Shipping weight*	28.79 lb (13.06 kg)	26.70 lb (12.11 kg)
Maximum supported weight (desktop orientation)	N/A	77.1 lb (35 kg)
Shipping box	19.69 x 12.2 x 23.62 in	9.72 x 19.68 x 22.67 in
dimensions (H x W x D)	500 x 310 x 600 mm	246.9 x 499.9 x 575.8 mm
* Configured with 1 hard dr	ive, 1 optical drive, no diskette drive, and no PCI	card.
Power Supply	320W power supply – active PFC	240W power supply – active PFC
Energy Efficient Power Supply	320W 89% efficient power supply – active PFC	240W 89% efficient power supply – active PFC
Ports		
USB 2.0	10 (4 fror	nt, 6 rear)
Serial	1 standard wi	th 2 nd optional
Parallel	1 ор	tional
D0/0		
PS/2	1 keyboar	d, 1 mouse
Video	-	d, 1 mouse grated graphics
-	analog for integ	
Video	analog for integ available via HP Displa	grated graphics
Video DVI output	analog for integ available via HP Displa 1 Standard DisplayPo Integrated High Definition a Front – mic ar	grated graphics yPort to DVI-D Adapter rt and 1 Standard VGA audio with internal speaker nd headphone
Video DVI output Support for Multi-Monitor	analog for integ available via HP Displa 1 Standard DisplayPo Integrated High Definition a Front – mic an Rear – input (supports micro	grated graphics yPort to DVI-D Adapter rt and 1 Standard VGA audio with internal speaker

		MT	SFF
Chipset	AMD 785G chipset	Х	Х



Standard Features and Configurable Components (availability may vary by country)

Processor	AMD Sempron Processors with HyperTransport™ Technology:		
One of the following	AMD Sempron 140 Processor (2.7 GHz, 1 MB L2 cache, HT bus 3.0)	Х	Х
	AMD Athlon II Dual-Core Processors with HyperTransport Technology:		
	AMD Athlon II X2 215 Processor (2.7 GHz, 2MB L2 cache, HT bus 3.0)	Х	Х
	AMD Athlon II X2 B22 Processor (2.8 GHz, 2 MB L2 cache, HT bus 3.0)	Х	Х
	AMD Athlon II X2 B24 Processor (3.0 GHz, 2 MB L2 cache, HT bus 3.0)	Х	Х
	AMD Phenom II Dual-Core Processors with HyperTransport Technology:		
	AMD Phenom II X2 B53 Processor (2.8 GHz, 1 MB L2 cache, 7 MB Total cache, HT bus 3.0)	Х	Х
	AMD Phenom II X2 B55 Processor 3.0 GHz, 1 MB L2 cache, 7 MB Total cache, HT bus 3.0)	Х	х
	AMD Phenom II Triple-Core Processors with HyperTransport Technology:		
	AMD Phenom II X3 B73 Processor 2.8 GHz, 1.5 MB L2 cache, 7.5 MB Total cache, HT bus 3.0)	Х	Х
	AMD Phenom II X3 B75 Processor 3.0 GHz, 1.5 MB L2 cache, 7.5 MB Total cache, HT bus 3.0)	Х	Х
	AMD Phenom II Quad-Core Processors with HyperTransport Technology:		
	AMD Phenom II X4 B93 Processor 2.8 GHz, 2 MB L2 cache, 8 MB Total cache, HT bus 3.0)	Х	Х
	AMD Phenom II X4 B95 Processor 3.0 GHz, 2 MB L2 cache, 8 MB Total cache, HT bus 3.0)	Х	Х
Memory	 Supports un-buffered non-ECC DDR3 SDRAM AMD processors support un-buffered non-ECC DDR3 SDRAM (synchronous dynamic access memory) at a frequency of up to 1333 MHz. NOTE: The actual memory speed for DDR3 SDRAM depends on the processor an configuration. The maximum speed of 1333 MHz requires an AMD Phenom II proc supports it. In addition, AMD Phenom II processors with CPUID 100F42h require than one DIMM slot per channel be populated with a DDR3 memory module in ord 	d memo essor th hat no r	ory nat nore

memory speed of 1333 MHz.

System memory upgrades are accomplished by adding DDR3 SDRAM module(s) to empty DIMM slots on the system board.

CAUTION: Voltage is supplied to the memory modules whenever the computer is connected to an active AC outlet. Adding or removing memory modules while voltage is present may cause irreparable damage to the memory modules or system board. The computer must be shut down with the AC power removed (disconnect AC power cord at rear chassis or at AC outlet) prior to adding or removing SDRAM modules.

HP recommends dual-channel configurations for the best memory performance.

For best performance, add memory to each memory channel and do not inter-mix memory module speeds. If memory module speeds are inter-mixed, the memory operating frequency will default to the slowest speed.



Standard Features and Configurable Components (availability may vary by country)

Microtower and Small Form Factor

Maximum Memory* Supports up to 16GB of un-buffered non-ECC DDR3 SDRAM.

The DIMM connectors for Channel A slot 3 and Channel B slot 4 are black and these slots must always be populated first in the channel. Not all possible memory configurations are represented in the table below.

NOTE: For systems configured with more than 3GB of memory and a 32-bit operating system, all memory may not be available to the OS due to system resource requirements. Addressing memory above 4GB requires a 64-bit operating system.

Total Memory	al Memory DIMM Slot Population						
	Char	nel A	Char	Channel B			
	1 (white)	3 (black)	2 (white)	4 (black)			
1-GB				1GB			
(Single Channel)							
2-GB		1GB		1GB			
(Dual Channel)							
3-GB		2GB		1GB			
(Dual Channel)							
4-GB		2GB		2GB			
(Dual Channel)							
4-GB	1GB	1GB	1GB	1GB			
(Dual Channel)							
8-GB	2GB	2GB	2GB	2GB			
(Dual Channel)							
16-GB maximum	4GB	4GB	4GB	4GB			
(Dual Channel)							

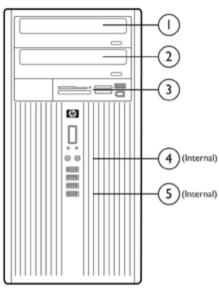
Expandability	Microtower	Small Form Factor
PCI slots	1 full-height	1 low-profile
Max power per slot	35W	35W
PCle x1 slot	2	2
Max power per slot	10W	10W
PCIe x16 slot	1 full-height	1 low-profile
Max power per slot	75W	35W
External Bays		
3.5"	1	1
5.25"	2	1
IDE		
Internal 3.5" HDD Bays	2	1
Hard Drive Controller (SATA) Supported	SATA	SATA
Hard Drive Interfaces Supported	SATA 3.0Gb/s	SATA 3.0Gb/s

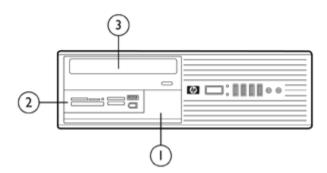


Standard Features and Configurable Components (availability may vary by country)



Small Form Factor





Storage - Drive Support							
	Microtower			Small Form Factor			
	Media Card Reader or Pocket Media Drive (optional)		3.5" Serial ATA Devices	Media Card5.25" Serial3.5" SerReader orATA DevicesATA DeviPocket MediaDrive(optional)			
Quantity Supported	1	2	2	1	1	2	
Position Supported	3	1,2	3,4,5	2	1	2,3	
Controller	USB/Diskette	SATA	SATA	USB/Diskette	SATA	SATA	

NOTE: The SATA port labeled SATA3 on the system board can be enabled by the BIOS as an eSATA port. Using it for an eSATA drive will require a separately purchased cable with an eSATA connector.

		МТ	SFF
Hard Drive	160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
One or two of the	250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
following	320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache,10,000 RPM, NCQ, Smart III)	Х	Х
	160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Х	Х
	3.5" Removable 160-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	3.5" Removable 250-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	3.5" Removable 500-GB SATA 3.0 Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 160-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 250-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 320-GB SATA 3.0-Gb/s Hard Drive (8MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х
	2 nd hard drive, 500-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 7200 RPM, NCQ, Smart IV)	Х	Х



Sidiludiu Fediules d	and Configurable Components (availability may vary by country)		
	2 nd hard drive, 80-GB SATA 3.0-Gb/s Hard Drive (16MB Cache,10,000 RPM, NCQ, Smart III)	Х	Х
	2 nd hard drive,160-GB SATA 3.0-Gb/s Hard Drive (16MB Cache, 10,000 RPM, NCQ, Smart III)	Х	Х
	RAID 0,1 support	Х	Х
	NOTE: NCQ functionality requires a user set-up BIOS setting.		
Solid State Drive	64-GB Solid State Drive	Х	Х
	RapidDrive	Х	Х
	NOTE: RapidDrive is an optional new productivity solution available only on the HF Pro. It links the Solid State Drive (SSD) and Hard Drive together to form one virtua combines the advantages of both technologies. Pre-installed applications reside c reduced access time, yet the usual limitations of SSD storage are eliminated by large hard drive.	I drive th on the SS	at SD for
Removable Storage –	Pocket Media Drive		
One or more of the following depending on	250GB Pocket Media Drive	Х	Х
form factor (see Storage	Media Reader		
- Drive Support section	HP 22-in-1 Media Card Reader (USB connection on the system board)	Х	Х
above)	HP 22-in1 (with 1394) Media Card Reader (USB connection on the system board) Optical Drives	Х	Х
	SATA DVD-ROM Drive	Х	Х
	SATA SuperMulti LightScribe DVD Writer Drive	X	Х
	SATA Blu-ray Writer	Х	Х
Security	TPM 1.2 Embedded Security Chip*	Х	Х
	HP Desktop Security lock kit (lock and cable)	Х	Х
	HP Chassis Security Kit	Х	Х
	Security cable with Kensington lock	Х	Х
	HP Solenoid Hood Lock and Sensor	Х	Х
	Optional HP ProtectTools 5.0 security software suite	Х	Х
	Optional LoJack Pro tracking and tracing subscription	Х	Х
	Optional USB Port Disable at factory (user configurable via BIOS)	Х	Х
	RAID 0,1 support * TPM module disabled where use is restricted by law; for example, Russia.	Х	Х
NIC	Broadcom NetXtreme Gigabit Ethernet BCM 5761 (integrated on system board)	Х	Х
	Broadcom NetXtreme Gigabit Ethernet Plus PCIe NIC	Х	Х
Wireless	HP 802.11 b/g/n Wireless PCIe x1 card (full height bracket)	Х	
	HP 802.11 b/g/n Wireless PCIe x1 card (low profile bracket)		X



Standard Featur	res and Configurable Components (availability may vary by country)		
Graphics	Integrated ATI Radeon HD 4200 Graphics*	Х	Х
-	ATI Radeon HD 4650 (1 GB DH) PCIe x16 Graphics Card	Х	
	ATI Radeon HD 4550 Dual Head PCIe x16 Graphics Card	Х	Х
	NVIDIA Quadro NVS 290 PCIe x1 Graphics Card	Х	Х
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x16 Graphics Card	Х	Х
	NVIDIA Quadro NVS 295 (256MB DH) PCIe x16 Graphics Card	Х	Х
	HP DisplayPort to VGA Adapter	Х	Х
	HP DisplayPort to DVI-D Adapter	Х	Х
	* Side Port memory: The AMD 785G chipset provides a Side Port memory interfac for 128 MB of dedicated frame buffer DDR3 memory with a device width of x16 for t graphics chip.		grated
Audio	Integrated High Definition audio with Realtek ALC261 codec (all ports are stereo)	Х	Х
	Microphone and Headphone front ports	Х	Х
	Line-out and Line-In rear ports*	Х	Х
	Multistreaming capable*	Х	Х
	Internal Speaker	Х	Х
	HP Thin USB Powered Speakers (optional)	Х	Х
	* Re-taskable ports; see technical specifications page 21.		
Input Devices	Keyboard - One of the following		
	HP PS/2 Standard Keyboard	Х	Х
	HP USB Standard Keyboard	Х	Х
	HP Smartcard Keyboard	Х	Х
	HP USB PS/2 Washable Keyboard	Х	Х
	HP USB Mini Keyboard	Х	Х
	Mouse - One of the following		
	USB 2-Button Laser Mouse	Х	Х
	PS/2 2-Button Optical Scroll Mouse	Х	Х
	USB 2-Button Optical Scroll Mouse	Х	Х
Miscellaneous	2 nd serial port adapter	Х	
	2 nd serial port adapter (low profile)		Х
	Parallel port adapter	Х	Х
	HP FireWire / IEEE 1394 Adapter	Х	Х
	Tower stand		Х



After-Market Options (availability may vary by region)

		МТ	SFF	Part Number
Communications	Wireless LAN	V	V	505774
	HP 802.11 b/g/n Wireless PCIe x1 card NICs	Х	Х	FS577A
	Broadcom NetXtreme Gigabit Ethernet Plus PCIe NIC	Х	х	EA833AA
	Modem			
	LSI PCIe x1 56K International SoftModem	Х	Х	FH970AA
Graphics	Multi head solutions			
-	ATI Radeon HD 4550 (256MB DH) PCIe x16 Card	Х	Х	AT042AA
	ATI Radeon HD 4650 (1 GB DH) PCIe x16 Graphics Card	Х		AR956AA
	HP DisplayPort to VGA Adapter	Х	Х	AS615AA
	HP DisplayPort to DVI-D Adapter	Х	Х	FH973AA
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x1 Graphics Card	Х	Х	KN586AA
	NVIDIA Quadro NVS 290 (256MB DH) PCIe x16 Graphics Card	Х	Х	KG748AA
Hard Drives	Serial ATA Hard Drives			
	HP 160-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	PY277AA
	HP 250-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	PY278AA
	HP 320-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	FH963AA
	HP 500-GB SATA 3.0-Gb/s 7200 rpm Hard Drive	Х	Х	KW347AA
	HP 80-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Х	Х	EM172AA
	HP 160-GB SATA 3.0-Gb/s 10,000 rpm Hard Drive	Х	Х	EW222AA
	HP Removable SATA Hard Drive Enclosure (Frame & Carrier)	Х	Х	RY102AA
	HP Removable SATA Hard Drive Enclosure (Carrier Only)	Х	Х	RY103AA
Input/Output Devices	HP PS/2 Standard Keyboard	Х	х	DT527A
	HP USB Standard Keyboard	Х	Х	DT528A
	HP USB Smartcard Keyboard	Х	Х	ED707AA
	HP USB Gray Standard Keyboard	Х	Х	DT529A
	HP USB PS/2 Washable Keyboard	Х	Х	VF097AA
	HP USB Mini Keyboard	Х	Х	AS601AA
	HP 2.4 GHz Wireless Keyboard and Mouse	Х	Х	NB896AA
	HP USB Laser Mouse	Х	Х	GW405AA
	HP PS/2 2-Button Optical Scroll Mouse	Х	Х	EY703AA
	HP USB 2-Button Optical Scroll Mouse	Х	Х	DC172B
Memory (DIMMs)	PC3-10600 (DDR3, 1333MHz) DIMMs Non-ECC			
	HP 4-GB PC3-10600 (DDR3 1333 MHz) DIMM	Х	Х	VH638AA
	HP 2-GB PC3-10600 (DDR3 1333MHz) DIMM	Х	Х	AT024AA
	HP 1-GB PC3-10600 (DDR3 1333 MHz) DIMM	Х	Х	AT023AA



Monitors	All HP monitors are supported that accept a graphics output provided by this PC. The LP3065 monitor can be supported by installing a graphics card that supports a dual-link DVI-D output.	у		
Multimedia	HP Thin USB Powered Speakers	Х	х	KU901AV
Optical Drives	DVD-ROM Drive			
	HP SATA DVD-ROM Drive DVD Writer	Х	Х	AH047AA
	SATA Blu-ray Writer	Х	Х	AR481AA
	HP SATA SuperMulti LightScribe DVD Writer Drive	Х	Х	GF343AA
Removable Storage	Removable Drives			
	HP 250GB Pocket Media Drive Multimedia	Х	Х	FE477AA
	HP 22-in-1 Media Card Reader	Х	Х	FX273AA
	HP 22-in-1 (with 1394) Media Card Reader	Х	Х	KN518AA
Security	Kensington lock	х	Х	PC766A
	HP Business PC Security Lock	Х	Х	PV606AA
	HP Chassis Security Kit	Х	Х	AR639AA
	HP ProtectTools 5.0 Client Security Software including HP ProtectTools Security Manager Credential Manager for HP ProtectTools Device Access Manager for HP ProtectTools Drive Encryption for HP ProtectTools Embedded Security for HP ProtectTools Java Card Security for HP ProtectTools LoJackPro for HP ProtectTools Privacy Manager for HP ProtectTools File Sanitizer for HP ProtectTools	Х	Х	TBD
	HP 2009 Wall Mount/Security Sleeve		Х	TBD
Manageability	HP Client Configuration Manager, Premium Edition	Х	Х	T3488AA (use T3489AA for 1000 licenses)
Brackets/Stands	HP 2009 Small Form Factor Tower Stand		Х	VN569AA
Miscellaneous	HP Serial Port Adapter Kit	Х	Х	PA716A
Accessories	HP Parallel Port Adapter Kit	Х	Х	KD061AA
	HP FireWire / IEEE 1394 Adapter	Х	Х	PA997A





Technical Specifications

Unit Environment and Operating Conditions	Microtower	Small Form Factor
General Unit Operating Guidelines		

neral Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)*	
	Non-operating: -22° to 140° F(-30° to 60° C)	
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)	
Maximum Altitude (unpressurized) Operating: 10,000 ft (3048 m) Non-operating: 30,000 ft (9144 m)		

* Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.

	Micro	otower	Small Fo	rm Factor
Power Supply	320-watt BTX power supply - Active PFC	320-watt 89% efficient* BTX power supply - Active PFC	240-watt BTX power supply - Active PFC	240-watt 89% efficient* BTX power supply - Active PFC
Operating Voltage Range	100-240VAC	100-240VAC	100-240VAC	100-240VAC
Rated Voltage Range	115V/230V	115V/230V	115V/230V	115V/230V
Rated Line Frequency	50/60 Hz	50/60 Hz	50/60 Hz	50/60 Hz
Operating Line Frequency Range	47-63 Hz	47-63 Hz	47-63 Hz	47-63 Hz
Rated Input Current	5.5A	5.5A	4A	4A
Heat Dissipation (NEED TO UPDATE)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1575 btu/hr (397 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1280 btu/hr (322 kg-cal/hr)	Typical 315 btu/hr (79 kg-cal/hr) Maximum 1260 btu/hr (317 kg-cal/hr)	Typical 270 btu/hr (68 kg-cal/hr) Maximum 1025 btu/hr (258 kg-cal/hr)
Power Supply Fan	Variable speed fan	Variable speed fan	Variable speed fan	Variable speed fan
ENERGY STAR Compliant		Х		Х
FEMP Standby Power Compliant (<1W in S5 - Power Off)**	Х	Х	Х	Х
Power Consumption in ENERGY STAR Mode - Suspend to RAM (S3) (Instantly Available PC)	<2.4W	<2.4W	<2.4W	<2.4W

Energy efficient power supply is a requirement for ENERGY STAR qualification in conjunction with a select range of processors and modules

** Power consumption in the Off/Apparent Off mode is measured and reported with the network interface controller "Wake on LAN" feature disabled in F10 Setup (default is "enabled").



Technical Specifications

ROM BIOS Information

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Business desktop computer into the enterprise, such as PXE, remote configuration, remote control, and F10 Setup support for 12 languages.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Security HP BIOS offers a robust and flexible set of security features to help the system administrator secure their systems from removal of sensitive data, and help prevent access by unauthorized users. Ability to disable USB ports.
- Tracking and tracing capabilities in case of theft available in select countries (subscription sold separately).
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies to assist in operating the HP Business Desktop computer in any enterprise environment.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Business Desktop computers, including BIOS updates from within DOS (Flashlite), BIOS updates from within Windows (HPQFlash, SSM), HP Client Manager, and fail-safe recovery. In addition, the HP Business Desktop BIOS Utilities tool enables replicated BIOS setup throughout the Enterprise; it is available from within the BIOS software and from the support website.

Additional HP BIOS Features

- Administrator password Also known as the setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS version cannot be changed and changes cannot be made to BIOS settings using F10 setup or under the OS.
- Advanced Configuration and Power Interface (ACPI) Represents a significant innovation in power and configuration management, allowing operating systems and applications to manage power based on activity and usage. Provides power conservation features under Windows XP.
- Mute internal speaker
- Disable USB ports

Other Features	Description
ACPI-Ready Hardware	Advanced Configuration and Power Management Interface (ACPI).
	 Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
SMBIOS Ver. 2.6	System Management BIOS, previously known as DMI BIOS, for system management information
Dual-State Power Button	Power button acts as both an on/off button and suspend-to-sleep button



Technical Specifications

Serviceability Features of System				
Dual Color Power LED on Front of Comp	outer (Indicates Normal Operations and Fau	It Conditions)		
Diagnostic LED Explanation Table				
System/Emergency ROM	Flash ROM	 CMOS Battery Holder for easy Replacement 		
Flash Recovery with Video	5 Aux Power LED on System PCA	 Processor ZIF Socket for easy Upgrade 		
Over-Temp Warning on Screen (Requires IM Agents) Clear Password Jumper DIMM Connectors for easy Upgrade				
Restore CD	Clear CMOS Switch	 NIC LEDs (integrated) (Green & Amber) 		

Serviceability Features of Chassis	• Oplan coordinated cables and		
 Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions 	 Color coordinated cables and connectors 	 Tool-less Hood Removal (thumbscrews for Microtower, spring-loaded latch for Small Form Factor) 	
 Front power switch 	System memory can be upgraded on Microtower without removing any internal components	 Tool-less Hard Drive, CD & Diskette Removal 	
Additional Features	Description		
Towerable	Small Form Factor can be oriented as a to	ower (in addition to desktop orientation)	
Drive Self Tests (DPS)	every sector of the hard drive for phy to the user.	cans critical physical components and ysical faults and then reports any faults ting system, it can be accessed through	
DPS Access through F10 Setup during Boot			
SMART IV Technology* (Self-Monitoring, Analysis and Reporting Technology)	 Predicts failures before they occur. indication parameters such as re-all calibration retry count By avoiding actual hard drive failures 	-	
DASH 1.1 support (Desktop and Mobile Architecture for System Hardware)	A standards initiative for representing out-o		
ASF 2.0 support (Alert Standard Format)	Industry-standard specification for network environments	alerting in operating system-absent	



Technical Specifications - Audio

High Definition Audio	Type High Definition Stereo Codec	Integrated Yes – 4-channel Realtek ALC261 codec
	Audio Jacks	Front microphone-In (150-K ohm Input Impedance)
		Rear Line-In/Microphone input (150-K ohm Input Impedance, function is configurable by audio driver)
		Rear Line-Out* (190 ohms Output Impedance, expects at least a 10-K ohm load)
		Front Headphone-Out (0.5 Ohm Output Impedance, expects at least a 32 ohm load)

NOTES:

Internal Speaker Amplifier is for Internal Speaker only. External Speakers need to be powered externally.

The rear input port can function as a Line-In or Microphone-In jack.

The front Microphone jack is retaskable to support headphones. When functioning as a headphone jack the same audio stream will be sent to both front jacks.

The front Microphone jack is also retaskable to function as a Line-in jack.

The Realtek Control Panel software required to reassign audio ports is preloaded but must be installed by the customer before these functions can be performed.

Multistreaming Capable Sampling	Multistreaming can be enabled in the Realtek control panel to allow independent audio streams to be sent to/from the front and rear jacks. 8 kHz – 192 kHz
Wavetable Syntheses (software)	Yes – Uses OS soft wavetable
Analog Audio	Yes
Number of Channels on Line-Out (mono/stereo)	Stereo (Left & Right channels)
Internal Audio Speake Power Rating	r 1.5 W
Internal Speaker	Yes; ability to mute internal speaker through F10 Setup
External Speaker Jack (Line-Out)	Yes



Technical Specifications - Communications

Integrated Broadcom	Connector	RJ-45	
NetXtreme Gigabit Ethernet BCM 5761	Controller	Broadcom 5761 PCI-Expr	
Ethernet Dow 5701	Memory	8 MB NVRAM serial Flas	h
	Data rates supported	10/100/1000 Mbps	
	Compliance	IEEE 802.1P, 802.1Q, 80	2.2, 802.3, 802.3AB, 802.3u, and 802.3x
	Bus architecture	PCI-E	
	Data path width	Single channel, PCI-E	
	Data transfer mode	Bus-master DMA	
	Power requirement	1.8W @ 3.3V	
	Boot ROM support	Yes	
	Network transfer mode	Full-duplex	
		Half-duplex (not available	for the 1000BASE-T transceiver)
	Network transfer rate	10BASE-T (half-duplex) 1	0 Mbps
		10BASE-T (full-duplex) 20) Mbps
		100BASE-TX (half-duplex) 100 Mbps
		100BASE-TX (full-duplex)	200 Mbps
		1000BASE-T (full-duplex)	2000 Mbps (actual rate limited by PCI Bus)
	Environmental	Operating temperature	32° to 131°F (0° to 55° C)
		Operating humidity	131° F (55° C) with 5% to 95% non-
			condensing humidity
	Management		, PXE 2.0, WfM 2.0, Broadcom mgmt utility,
	capabilities	ASF2.0, DASH 1.0 and D	ASH 1.1 profiles
Broadcom NetXtreme	Connector	RJ-45	
Gigabit Ethernet Plus	Controller	Broadcom 5761 PCI-Expr	ress LAN Controller
Gigabit Ethernet Plus PCIe NIC Card	Controller Memory	Broadcom 5761 PCI-Expr 8 MB NVRAM serial Flas	
-		•	
-	Memory	8 MB NVRAM serial Flas 10/100/1000 Mbps	
-	Memory Data rates supported	8 MB NVRAM serial Flas 10/100/1000 Mbps	h
-	Memory Data rates supported Compliance	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80	h
-	Memory Data rates supported Compliance Bus architecture	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E	h
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and	h 12.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682)
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver)
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex)	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex)	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps 100 Mbps 200 Mbps
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex) 100BASE-TX (full-duplex)	h 22.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps 100 Mbps 200 Mbps 1 200 Mbps (actual rate limited by PCI Bus)
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex) 100BASE-TX (full-duplex) 00BASE-T (full-duplex)	h 2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps 100 Mbps 200 Mbps 2000 Mbps 2000 Mbps (actual rate limited by PCI Bus) 32° to 131°F (0° to 55° C)
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex) 100BASE-TX (full-duplex)	h 22.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps 100 Mbps 200 Mbps 1200 Mbps (actual rate limited by PCI Bus)
-	Memory Data rates supported Compliance Bus architecture Data path width Data transfer mode Hardware certifications Power requirement Boot ROM support Network transfer mode	8 MB NVRAM serial Flas 10/100/1000 Mbps IEEE 802.1P, 802.1Q, 80 PCI-E Single channel, PCI-E Bus-master DMA FCC class B, Canada and for Taiwan, VCCI for Japa (E212044), European Uni 1.8W @ 3.3V Yes Full-duplex Half-duplex (not available 10BASE-T (half-duplex) 1 10BASE-T (full-duplex) 20 100BASE-TX (half-duplex) 100BASE-TX (full-duplex) 1000BASE-TX (full-duplex) 00perating temperature Operating humidity	h b2.2, 802.3, 802.3AB, 802.3u, and 802.3x d US NRTL Mark, C-Tick for Australia, BSMI an, MIC for Korea, GOST for Russia, UL listed on Notice (CE 0682) for the 1000BASE-T transceiver) 0 Mbps 0 Mbps 0 Mbps 100 Mbps 200 Mbps 200 Mbps 2000 Mbps (actual rate limited by PCI Bus) 32° to 131°F (0° to 55° C) 131° F (55° C) with 5% to 95% non-



Technical Specifications - Communications

P802.11b/g/m Wireless PCle x1 Card Dimensions (L x H) 3.3 x 4.7 inches (8.5 x 12 cm) Weight 0.08 pounds (40 g) Controller Raink R12790 System Interface POIExpress x1 Frequency band 2400 - 2.497 GHz Oporating tomporature 10° to 150°C, operating) Storage temperature 40° to 170°C, non-operating) Humidity 10-90% operating 12V +/ 8% Power consumption Power consumption Platform/VLAN Mode Power Consumption Maximum Power 10 Wats consumption Transmit Packet or 1000 mA peak current for 100 microseconds or ologer Active Scanning 3Watts maximum averaged over 1 second ide without IEEE PSP Pattor off in software SurW maximum, averaged over 1 second ide without GFI Express Card Duby power 802.11b modes SurW maximum, averaged over 1 second ide without GFI Express Card Duby power 802.11b modes SurW maximum averaged over 1 second ide power removed for maximum Low Portie PCI Express Card SurW maximum, averaged over 1 second ide power removed for maximum Low Portie PCI Express Card SurW maximum averaged over 1 second ide power removed for maximum SurW maximum averaged over 1 secon		Management capabilities	ACPI, WOL and DMI 2.0, PXE 2.0, WfM 2.0, Broadcom mgmt utility, ASF2.0, DASH 1.0 and DASH 1.1 profiles			
NotightDoub pounds (et g)ControllerRalink RT2790System interfacePOEExpress x1Network standard802.11 biginFrequency band2.400 - 2.497 GHzOperating temperature40° to 170°F, non-operating (-10° to 65°C, operating)Storage temperature40° to 170°F, non-operating (-40° to 80°C, non-operating)Humidity10-90% operating545% non-operating545% non-operatingOperating voltage3.31 + 1-9% 12V +/- 8%Power consumptionPattorm/WLAN ModePower consumptionPattorm/WLAN ModeTransmit Packet or Ide without IEEE PSP mode enabled100 WattsReceive Only Mode or Ide without IEEE PSP Receive Only Mode or Ide without IEEE PSP 	HP 802.11b/g/n		3.3 x 4.7 inches (8.5 x 12	2 cm)		
System interface Network standard PCIExpress x1 Frequency band 202.11 b/g/n Frequency band 24.02 - 24.97 GHz Storage temperature 40° to 170°F, non-operating (-40° to 80°C, non-operating)	Wireless PCle x1 Card	Weight	0.08 pounds (40 g)			
Network standard 802.11 b/g/n Frequency band 2.400 - 2.497 GHz Operating temperature 41° to 176°F, non-operating (-40° to 80°C, non-operating) 10-90% operating 5-95% non-operating (-40° to 80°C, non-operating) Operating tougate 3.3V +/- 9% 12V +/- 8% Power consumption Power consumption Power Consumption Maximum Power 10 Watts Consumption 4 Watts maximum averaged power over 1 second Transmit Packet or 1000 mA peak current for 100 microseconds or longer ridle with UEEE PSP 1.0 Watts maximum averaged over 1 second Idle, with IEEE PSP 1.0 Watts maximum averaged over 1 second (upport from in S3 or S4 5mW maximum, averaged over 1 second (upport from in S3 or S4 5mW maximum, averaged over 1 second (upport from in S3 or S4 5mW maximum, averaged over 1 second (upport from in S0 or S4 5mW maximum, averaged over 1 second (upport from in S3 or S4 5mW maximum, averaged over 1 second (upport from in S0 or S4 5mW maximum, averaged over 1 second (upport from in S0 or S4 5mW maximum, averaged over 1 second (upport fr		Controller	Ralink RT2790			
Frequency band 2.400 - 2.497 GHz Operating temperature 14' to 149'F, operating (-10° to 65'C, operating) Storage temperature 40° to 176'F, operating (-10° to 65'C, operating) Storage temperature 10° to 176'F, operating (-10° to 85'C, operating) Operating voltage 595% non-operating 595% non-operating Operating voltage 2.400 - 2.497 GHz Power consumption Pattorm/WLAN Mode Maximum Power 10 Watts Consumption 10 Watts maximum averaged power over 1 second Transmit Packet or Active Scanning 1000 mA peak current for 100 microseconds or longer Receive Only Mode or Mode enabled 3 Watts maximum averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sabled 50 mW maximum, averaged over 1 second (turned off in software) Platform ID Sable 50 mW maximum, av		System interface	PCIExpress x1			
Operating temperature 14° to 149°F, operating (-10° to 55°C, operating) 40° to 176°F, non-operating (-40° to 80°C, non-operating) Humidity 10.90% operating 5-95% non-operating (-40° to 80°C, non-operating) Operating voltage 3.3V +/- 9% 20° to 176°F, non-operating Power Consumption Power consumption Platform/WLAN Mode Maximum Power Consumption Power Consumption Transmit Daket or Active Scanning 100 watts 100 watts Receive Only Mode or Ide without IEEE PSP mode enabled 100 watts maximum averaged over 1 second Ude with Ut (EE PSP mode enabled 10.0 watts maximum averaged over 1 second Very Profile PCI Express 50 mW maximum, averaged over 1 second Cutput power (approximately) 802.110 modes 50 mW maximum, averaged over 1 second Low Profile PCI Express 50 mW maximum, averaged over 1 second Cutput power (approximately) 802.110 modes 812.119 modes #17 dBm +/- 1.0 dB maximum Receive sensitivity Mode Data rate Sensitivity chains Receive sensitivity Mode Data rate Sensitivity chains 802.119 6 Mbps -94 dBm 802.119 6 Mbps -94 dBm 802.119		Network standard	802.11 b/g/n			
Storage temperature Humidity 40° to 178°F, non-operating 5-95% non-operating 5-95% non-operating 12/ +/-8%		Frequency band	2.400 - 2.497 GHz			
Humidity 10-90% operating 5-95% non-operating 5-95% non-operating 12V +/- 8% Power consumption Power consumption Patterm/WLAN Mode 12V +/- 8% Power Consumption Power consumption Patterm/WLAN Mode 12V +/- 8% Power Consumption Transmit Only 4 Watts maximum averaged power over 1 second Transmit Packet or Active Scanning 1000 mA peak current for 100 microseconds or longer Receive Only Mode or Idle without IEEE PSP mode enabled 1.0 Watts maximum averaged over 1 second Transmit Disabled (turned off in software) 50 mW maximum, averaged over 1 second Platform in S3 or S4 (power removed from Low Profile PCI Express Card) 50 mV maximum, averaged over 1 second Output power (approximately) 802.11b modes +19 dBm +/- 1.0 dB maximum 802.11g modes +17 dBm +/- 1.0 dB maximum #17 dBm +/- 1.0 dB maximum Receive sensitivity Mode 802.11b 1 Mbps -94 dBm 802.11g 6 Mbps -91 dBm 802.11g 6 Mbps -92 dBm </td <td></td> <th>Operating temperature</th> <td>14° to 149°F, operating (-</td> <td>-10° to 65°C, operating)</td> <td></td>		Operating temperature	14° to 149°F, operating (-	-10° to 65°C, operating)		
5-95% non-operating 3.3V +/- 9% 12V +/-8% Power consumption Power consumption Power consumption Platform/WLAN Mode Maximum Power Consumption Power Consumption Transmit Only 4 Watts maximum averaged power over 1 second Transmit Packet or Active Scanning 1000 mA peak current for 100 microseconds or longer 3 Watts maximum averaged over 1 second Idle without IEEE PSP mode enabled 100 Watts maximum averaged over 1 second Idle, with IEEE PSP mode enabled Idle, with IEEE PSP mode enabled 1.0 Watts maximum averaged over 1 second (turned off in software) Platform in S3 or S4 (power removed from Low Profile PCI Express Card) 5mW maximum, averaged over 1 second Output power (approximately) 802.119 modes +19 dBm +/-1.0 dB maximum 5mW maximum, averaged over 1 second Mode Data rate Sensitivity 802.110 1 Mbps 94 dBm maximum 802.111 1 Mbps 94 dBm 802.112 6 Mbps 94 dBm 802.113 6 Mbps 94 dBm 802.114 1 Mbps 85 dBm 802.115 11 Mbps 85 dBm 802.116 6 Mbps 94 dBm 802.119 6 Mbps 94 dBm 802.119 6		Storage temperature	-40° to 176°F, non-operating (-40° to 80°C, non-operating)			
12V +/- 8% Power consumption Platform/VLAN Mode Power Consumption 10 Watts 10 Watts Consumption Transmit Only 4 Watts maximum averaged power over 1 second Transmit Packet or 1000 mA peak current for 100 microseconds Active Scanning 000 mA peak current for 100 microseconds Receive Only Mode or Idle without IEEE PSP 3 Watts maximum averaged over 1 second Idle without IEEE PSP 1.0 Watts maximum averaged over 1 second Idle without IEEE PSP 1.0 Watts maximum averaged over 1 second Idle without IEEE PSP 1.0 Watts maximum, averaged over 1 second Idle without IEEE PSP 1.0 Watts maximum, averaged over 1 second Votput power 50 mW maximum, averaged over 1 second Votput power 802.11b modes 50 mW maximum, averaged over 1 second (approximately) 802.11b modes 50 mW maximum, averaged over 1 second Mode Data rate Second 802.11b modes 802.11b modes 17 dBm +/- 1.0 dB maximum 11 Mbps -94 dBm 802.11g 6 Mbps -91 dBm 802.11g 6 Mbps -72 dBm 802.11g 6 Mbps -72 dB		Humidity				
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SecondTransmit Packet or Active Scanning Receive Only Mode or Idle without IEEE PSP mode enabled100 mA peak current for 100 microseconds or longerWatts maximum averaged over 1 second3 Watts maximum averaged over 1 secondIdle, with IEEE PSP mode enabled1.0 Watts maximum averaged over 1 secondIdle, with IEEE PSP mode enabled1.0 Watts maximum averaged over 1 secondTransmit Disabled (turned off in software)50 mW maximum, averaged over 1 secondPlatform in S3 or S4 (power removed from Low Profile PCI Express Card)50 mW maximum, averaged over 1 secondOutput power (approximately)802.11b modes +19 dBm +/- 1.0 dB maximum802.11g modes +17 dBm +/- 1.0 dB maximumEWC modes +17 dBm +/- 1.0 dB maximumReceive sensitivityMode 802.11bData rate 802.11bSensitivity802.11b11 Mbps-94 dBm 802.11g804 dBm 802.11g802.11g6 Mbps-91 dBm 802.11g-91 dBm 802.11g802.11g18 Mbps-75 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-73 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-74 dBm 802.11g802.11g54 Mbps-74 dBm 802.11g802.11g54 Mbps-74 dBm 				10 Watts		
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mode enabledTransmit Disabled (turned off in software)50 mW maximum, averaged over 1 second (turned off in software)Platform in S3 or S4 (power removed from Low Profile PCI Express Card)5 mW maximum, averaged over 1 secondOutput power (approximately)802.11b modes +19 dBm +/- 1.0 dB maximum802.11g modes +17 dBm +/- 1.0 dB maximumEWC modes +17 dBm +/- 1.0 dB maximumReceive sensitivityModeData rateSensitivity802.11b1 Mbps-94 dBm -94 dBm 802.11g-94 dBm -85 dBm 802.11g802.11g18 Mbps-85 dBm -85 dBm 802.11g802.11g802.11g54 Mbps-75 dBm -85 dBm -75 dBm 802.11g87 dBm -72 dBm -72 dBm -72 dBm -72 dBm -72 dBm -72 dBm -72 dBm EWC (2.4 GHz)54 Mbps-78 dBm -78 dBmEWC (2.4 GHz)54 Mbps-78 dBm -74 dBm -74 dBm-74 dBmEWC (2.4 GHz)54 Mbps-74 dBm -74 dBmEWC (2.4 GHz)54 Mbps-74 dBm			Idle without IEEE PSP	3 Watts maximum avera	ged over 1 second	
(turned off in software)Platform in S3 or S4 (power removed from Low Profile PCI Express Card)5 mW maximum, averaged over 1 secondOutput power (approximately)802.11b modes +19 dBm +/- 1.0 dB maximum802.11g modes +17 dBm +/- 1.0 dB maximumEWC modes +17 dBm +/- 1.0 dB maximum (total power in all transmit chains)Receive sensitivityMode 802.11bData rate 1 MbpsSensitivity -94 dBm 802.11bSensitivity -94 dBm 802.11b802.11b1 Mbps-94 dBm 802.11g-94 dBm 802.11g-94 dBm 802.11g802.11g1 Mbps-94 dBm 802.11g-91 dBm 802.11g802.11g18 Mbps-91 dBm 802.11g802.11g48 Mbps-75 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-72 dBm 802.11g802.11g54 Mbps-73 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g54 Mbps-78 dBm 802.11g802.11g162 Mbps-74 dBm 802.11g802.11g62 Mbps-74 dBm 802.11g802.11g52 Mbps-74 dBm 802.11g802.11g52 Mbps-68 dBm				1.0 Watts maximum ave	raged over 1 second	
(power removed from Low Profile PCI Express Card) 802.11g modes +19 dBm +/- 1.0 dB maximum Receive sensitivity 802.11b modes +17 dBm +/- 1.0 dB maximum 802.11b 802.11b 802.11b 802.11b 802.11b 802.11b 802.11b 802.11g 802.11				50 mW maximum, avera	ged over 1 second	
(approximately)+19 dBm +/- 1.0 dB maximum+17 dBm +/- 1.0 dB maximum+17 dBm +/- 1.0 dB maximum+17 dBm +/- 1.0 dB maximumReceive sensitivityModeData rateSensitivity802.11b1 Mbps-94 dBm802.11b11 Mbps-94 dBm802.11g6 Mbps-91 dBm802.11g18 Mbps-85 dBm802.11g18 Mbps-85 dBm802.11g48 Mbps-75 dBm802.11g54 Mbps-72 dBm802.11g54 Mbps-82 dBmEWC (2.4 GHz)54 Mbps-82 dBmEWC (2.4 GHz)54 Mbps-78 dBmEWC (2.4 GHz)162 Mbps-74 dBmEWC (2.4 GHz)162 Mbps-74 dBmEWC (2.4 GHz)270 Mbps-68 dBm			(power removed from Low Profile PCI Express	5 mW maximum, averag	ed over 1 second	
No definition in definition		Output power	802.11b modes	802.11g modes	EWC modes	
802.11b 1 Mbps -94 dBm 802.11b 11 Mbps -85 dBm 802.11g 6 Mbps -91 dBm 802.11g 18 Mbps -85 dBm 802.11g 18 Mbps -75 dBm 802.11g 54 Mbps -72 dBm 802.11g 54 Mbps -72 dBm 802.11g 54 Mbps -87 dBm 802.11g 54 Mbps -72 dBm EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm		(approximately)			maximum (total power in all transmit	
802.11b 11 Mbps -85 dBm 802.11g 6 Mbps -91 dBm 802.11g 18 Mbps -85 dBm 802.11g 18 Mbps -85 dBm 802.11g 48 Mbps -75 dBm 802.11g 54 Mbps -72 dBm 802.11g 54 Mbps -87 dBm EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -78 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm		Receive sensitivity	Mode	Data rate	Sensitivity	
802.11g6 Mbps-91 dBm802.11g18 Mbps-85 dBm802.11g48 Mbps-75 dBm802.11g54 Mbps-72 dBm802.11g54 Mbps-87 dBmEWC (2.4 GHz)6.5 Mbps-87 dBmEWC (2.4 GHz)54 Mbps-82 dBmEWC (2.4 GHz)81 Mbps-78 dBmEWC (2.4 GHz)162 Mbps-74 dBmEWC (2.4 GHz)270 Mbps-68 dBm			802.11b	1 Mbps	-94 dBm	
802.11g 18 Mbps -85 dBm 802.11g 48 Mbps -75 dBm 802.11g 54 Mbps -72 dBm 802.11g 54 Mbps -72 dBm EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -82 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			802.11b	11 Mbps	-85 dBm	
802.11g 48 Mbps -75 dBm 802.11g 54 Mbps -72 dBm EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -82 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			802.11g	6 Mbps	-91 dBm	
802.11g 54 Mbps -72 dBm EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -82 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			802.11g	18 Mbps	-85 dBm	
EWC (2.4 GHz) 6.5 Mbps -87 dBm EWC (2.4 GHz) 54 Mbps -82 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			802.11g	48 Mbps	-75 dBm	
EWC (2.4 GHz) 54 Mbps -82 dBm EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			802.11g	54 Mbps	-72 dBm	
EWC (2.4 GHz) 81 Mbps -78 dBm EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			EWC (2.4 GHz)	6.5 Mbps	-87 dBm	
EWC (2.4 GHz) 162 Mbps -74 dBm EWC (2.4 GHz) 270 Mbps -68 dBm			EWC (2.4 GHz)	54 Mbps	-82 dBm	
EWC (2.4 GHz) 270 Mbps -68 dBm			EWC (2.4 GHz)	81 Mbps	-78 dBm	
			EWC (2.4 GHz)	162 Mbps	-74 dBm	
EWC (2.4 GHz) 300 Mbps -64 dBm			EWC (2.4 GHz)	270 Mbps	-68 dBm	
			EWC (2.4 GHz)	300 Mbps	-64 dBm	



Technical Specifica	tions - Communicati	ons	
	Data transfer rate	Data Rate (MCS)	Minimum Throughput
		1 Mbps (802.11 b)	700 kbps
		2 Mbps (802.11 b)	1.4 Mbps
		5.5 Mbps (802.11 b)	3.5 Mbps
		11 Mbps (802.11 b)	5.9 Mbps
		12 Mbps (802.11 g)	6 Mbps
		18 Mbps (802.11 g)	9 Mbps
		24 Mbps (802.11 g)	12 Mbps
		36 Mbps (802.11 g)	18 Mbps
		48 Mbps (802.11 g)	21 Mbps
		54 Mbps (802.11 g)	22.5 Mbps
		6.5 Mbps (20 MHz EWC)	4.5 Mbps
		13 Mbps (20 MHz EWC)	9 Mbps
		19.5 Mbps (20 MHz EWC)	13.5 Mbps
		26 Mbps (20 MHz EWC)	18 Mbps
		39 Mbps (20 MHz EWC)	27 Mbps
		52 Mbps (20 MHz EWC)	36 Mbps
		58.5 Mbps (20 MHz EWC)	40 Mbps
		65 Mbps (20 MHz EWC)	45 Mbps
		78 Mbps (20 MHz EWC)	54 Mbps
		104 Mbps (20 MHz EWC)	72 Mbps
		117 Mbps (20 MHz EWC)	81 Mbps
		130 Mbps (20 MHz EWC)	91 Mbps
		13.5 Mbps (40 MHz EWC)	8 Mbps
		27 Mbps (40 MHz EWC)	16 Mbps
		40.5 Mbps (40 MHz EWC)	24 Mbps
		54 Mbps (40 MHz EWC)	32 Mbps
		81 Mbps (40 MHz EWC)	48 Mbps
		108 Mbps (40 MHz EWC)	64 Mbps
		121.5 Mbps (40 MHz EWC)	72 Mbps
		135 Mbps (40 MHz EWC)	81 Mbps
	Security	IEEE and WiFi conAES: CCM	npliant 64 / 128 bit WEP encryption
		 802.1x authenticati WPA: 802.1x. WPA WPA2 certification IEEE 802.11i Ciese Cartified Extra 	A-PSK and TKIP
	Antonno		ensions, all versions through V5
	Antenna Certifications	HP part number 497792-0 Wi-Fi certified	
	Certifications	United States, Canada, P	Peru Taiwan
••••••••••••••••••••••••••••••••••••••	by country	United States, Sallaud, F	Giu, Taiwan



Technical Specifications - Communications

LSI PCIe x1 56K International	Data Transmission	Technology speeds: 56,000 Kbps maximum downstream data, controllerless
SoftModem		NOTE: 56 Kbps technology refers to download speeds only and requires compatible modems at server sites. Other conditions may limit modem speed. FCC limitations allow a maximum of 53 Kbps during download transmissions.
	Data Speeds	(Upload only) 33,600/31,200/28,800/26,400/21,600/19,200/ 16,800/14,400/12,000/9,600/7,200/4,800/2,400/1,200/300
	Data Standards	ITU-T V.90, ITU-T, ITU-T V.34, V.44, V.42, V.42bis21, V.32bis, Bell 212A, and Bell 103
	Fax Speeds	14,400/12,000/9,600/7,200/4,800/2,400/1,200/300 b/s
	Fax Mode Capabilities	ITU-T T.31 class 1 FAX, V. 17, V.29, V.27ter, and V.21 Channel 2
	Error Correction and Data Compression	V.44, 42bis, V.42 and MNP2-5
	Power Management	PCI Bus Power Management Interface Specification (PCI-PM) Revision 1.2, Appendix A. D0, D3hot, and D3cold. Wake on Ring state when in D3cold. If the power management event (PME) feature is enabled in D3cold, a modem can wake the system via WAKE# (WAKEN) or beacon. Meets PCI Express 1.1 standard.
	Upgradeability	Driver upgradeable for future enhancements
	Video	ITU-T V.80 video ready interface
	Other	TIA/EIA 602 standard AT command set
		Integrated DTE interface with speeds of up to 115.2 Kbps, parallel 16550a UART-compatible interface
		Optional ring wakeup signal
	Operating Temperature	e 32° to 158° F (0° to 70° C)
	Operating Humidity	20% to 90%, non-condensing
	Power	Requires a 3.3-V auxiliary power rail on PCI express bus
		Uses only one PCI express load (i.e., one grant/request pair), one shared IRQ, one electrical load
	Chipset	LSI SV92EX - Integrated PCI interface with 3.3-V tolerant buffers and CardBus support
	Dimensions (L X H)	Complies with PCI express low profile specifications-6.7 x 2.3 in (17.0 x 5.8 cm) and supports high- and low-profile brackets
	Connection	Single RJ-11 connector
	Other Features	Digital line protection, call progress monitoring via on-board piezo device, support for high profile and low profile brackets, PnP ID support
	Safety	UL recognized to UL 1950, 3 rd edition (U.S. and Canada); IEC 950 (TUV, NEMKO, DEMKO, SEMKO); CE Mark, EC 950 (TUV, NEMKO, DEMKO, SEMKO, CE mark
	EMC	FCC Part 15, IC ES003, EN 55022, 3 rd edition, EN 55024, annex A, EN 61000-4-6, EN 61000-4-8
	Telecom	FCC Part 68, IC-CS-03 (Canada); Worldwide PTT approvals Not available in Korea or the Republic of South Africa.
	Other	The SV92EX device is packaged in a 32-pin micro leadless chip carrier (MLCC). The SV92EX is fully compliant with the PCI Express revision 1.1 specification. WHQL approved; ASPM compliant.



Integrated ATI HD 4200	Memory	Variable and User selectable in BIOS s	settings			
Gaphics	Controller Clock Speed 500MHz					
	Maximum Color Depth					
	•	Yes				
		DX10, OpenGL 2.0				
	• •	1 VGA, 1 DisplayPort (Multi-Mode (DP	++) 1.1a compliant)			
	-	400 MHz	, , ,			
Resolutions	Resolution	Maximum Refres	sh Rate (Hz)			
Supported		Analog Connection	Digital Connection			
	640x480	85	60			
	800x600	85	60			
	1024x768	85	60			
	1280x720	85	60			
	1280x1024	85	60			
	1440x900	75	60			
	1600x1200	85	60			
	1680x1050	75	60			
	1920x1080	85	60			
	1920x1200	85	60			
	1920x1440	85	60			
	2048x1536	75	60			
	2560x1600		60			
ATI Radeon HD 4650 (1	Bus type	PCI Express (x16 lanes)				
GB DH) PCIe x16 Graphics Card (FH	Maximum vertical refres	1 ()				
Only)	Display support	Integrated 400 MHz RAMDAC				

DH) PCIe x16 phics Card (FH	Maximum vertical refresh rate	85 Hz		
y)	Display support	Integrated 400 MHz RAMDAC		
	Display max resolution	2560 x 1600 digital, 2048 x 1536 analog		
	Board display options	Supports two displays through any combination of two of the three output ports.		
	Board configuration	Specification	Description	
		Graphics Chip	RV730Pro	
		Core clock	600 MHz	
		Memory clock	500 MHz	
		Frame buffer	1 GB DDR2, 128 bit wide	
	Maximum power	55 W		
	Languages supported	24 languages: English, Arabic, Chinese Simplified, Chinese Traditional, Czechoslovakian, Danish, Dutch, Finnish, French, German, Greek, Hebrew, Hungarian, Italian, Japanese, Korean, Norwegian, Polish, Portuguese, Russian, Spanish, Swedish, Thai, Turkish		
	Compliance standards	EMC Emissions: a) CISPR22: 1997/EN 55022:1998 - Class B - Limits an measurement of radio disturbance characteristics of Info Technology Equipment		
			1998 - Information Technology Equipment - Limits and Methods of Measurement.	



ATI Radeon HD 4650 (1 GB) PCIe x16 Graphics Card display resolutions and refresh rates NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Refresh Rate (Hz)		
Resolution	Analog Connection	Digital Connectior	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R*	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	60**	

* Max HDMI resolution is 1080p

** Only supported when using a dual-link DVI connection

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

ATI Radeon HD 4550	Bus type	PCI Express (x16 lanes)		
(256 MB DH) PCIe x16 Graphics Card	Maximum vertical refresh rate	85 Hz		
	Display support	Integrated 400 MHz RAMDAC		
	Display max resolution	1900 x 1200 digital, 2048 x 1	1536 analog	
	Board display options		cluded DMS-59 to dual VGA cable or 2 /IS-59 to dual DVI cable kit part number: deo connector for TV output	
	Board configuration	Specification	Description	
		Graphics Chip	RV710	
		Core clock	600MHz	
		Memory clock	800 MHz	
		Frame buffer	256 MB DDR2, 64 bit wide	
	Languages supported	 Traditional, Czechoslovakian, Danish, Dutch, Finnish, F German, Greek, Hebrew, Hungarian, Italian, Japanese, I Norwegian, Polish, Portuguese, Russian, Spanish, Swe Turkish ards <u>EMC Emissions</u>: a) FCC Part 15, Subpart B - Unintentional Radiators, CI Computing Devices for Home & Office Use b) CISPR22: 1997/EN 55022:1998 - Class B - Limits an measurement of radio disturbance characteristics of Info Technology Equipment c) Canadian Standard ICES-003 is equivalent to CISPR2 d) Taiwanese Standard BSMI e) Japanese VCCI f) Australian C-Tick g) Korean (KCC) 		
	Compliance standards			
		EMC Immunity: CISPR 24:1997/EN 55024:19	998 - Information Technology Equipment	



- Immunity Characteristics - Limits and Methods of Measurement.

ATI Radeon HD 4550 DH PCIe x16 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.

	Maximum Ref	fresh Rate (Hz)
Resolution	Analog Connection	Digital Connection
640x480	85	60
800x600	85	60
1024x768	85	60
1280x720	85	60
1280x1024	85	60
1440x900	75	60
1600x1200	85	60
1680x1050	75	60
1920x1080	85	60-R
1920x1200	85	60-R
1920x1440	85	N/A
2048x1536	75	N/A
2560x1600	N/A	N/A

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

NVIDIA Quadro NVS 290 PCIe x1 Graphics	Bus type	PCIe x1 Low profile, both ATX and low profile brackets included		
Card	Graphics Controller	•	raphics processor unit (GPU)	
	Memory	256 MB DDR2		
	Connector	Single high-density DMS-59	Flex Connector	
	Dimensions	Low-profile, 2.586 x 6.6 in (6	6.57 x 16.76 cm)	
	Multi-monitor support	Dual analog or digital (Single Link DVI) monitors (DVI support requires optional DVI cable kit DL139A)		
	RAMDAC	Dual 350 MHz (integrated)		
	Maximum pixel clock	350 MHz		
	Overlay planes	One 1-bit Video overlay plane		
	High-definition Video Processor (HDVP)	Full screen, full frame video playback of HDTV and DVD content DVD-ready motion compensation for MPEG-2 Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0) IDCT motion compensation 5-tap horizontal by 3-tap vertical filtering 8:1 up/down scaling		
	Input/Output connectors	DMS-59		
	Board display options	Supports two displays via included DMS-59 to dual VGA cable or DVI monitors via optional DMS-59 to dual DVI-I single-link connect cable kit part number: DL139A.		
	Board configuration	Specification	Description	
		Description	G86-825	
		Core clock	460 MHz	
		Memory clock	400 MHz	
		Frame buffer	256 MB DDR2, 64 bit wide	
	Quadro NVS 290 PCIe x1 (Franhics Card display resol	utions and refresh rates	

NVIDIA Quadro NVS 290 PCIe x1 Graphics Card display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as the may not have been tested and qualified by HP.



	Maximum Refresh Rate (Hz)		
Resolution	Analog Connection	Digital Connection	
640x480	85	60	
800x600	85	60	
1024x768	85	60	
1280x720	85	60	
1280x1024	85	60	
1440x900	75	60	
1600x1200	85	60	
1680x1050	75	60	
1920x1080	85	60-R	
1920x1200	85	60-R	
1920x1440	85	N/A	
2048x1536	75	N/A	
2560x1600	N/A	N/A	

NOTE: 60-R denotes reduced blanking timings are used on single-link DVI connections and may be used with other digital connections.

NVIDIA Quadro NVS	Form Factor	Low Profile
290 256MB Dual Head	Bus Type	PCle x16
PCIe x16 Graphics Card	Memory	256 MB 400MHz DDR2 SDRAM unified frame buffer, Z-buffer and Texture storage
	Connector	DMS-59, includes DMS-59 to Dual DVI-I cable. DMS-59 to Dual VGA cable available as an option.
	Display Resolution Support	Dual integrated analog display controllers supporting up to two analog displays at 2048x1536 @ 85Hz on both displays or dual digital displays at 1920x1200 (single-link). nVIEW advanced multi-display desktop and application management seamlessly integrated into Microsoft Windows
	RAMDAC	Integrated dual 400MHz
	Color planes	32-bit color buffer
	Overlay planes	Hardware supported
	nView architecture	Advanced multi-display desktop & application management seamlessly integrated into Microsoft Windows.
	Multi-Monitor support	Dual monitor support
	DVI support	DMS-59 (to dual DVI-SL)
	High-definition Video Processor (HDVP)	Full-screen, full-frame video playback of HDTV and DVD content DVD-ready motion compensation for MPEG- 2Independent hardware color controls for video overlay Hardware color-space conversion (YUV 4:2:2 and 4:2:0) IDCT motion compensation 5-tap horizontal by 3-tap vertical filtering 8:1 up/down scaling
	Supported graphics APIs	OGL 2.1 & DX10 Support; Shader Model 4.0
HP DisplayPort to DVI-	Connectors	DisplayPort and DVI-D single link connector
D Adapter	Adapter length	7.5 in (19.0 cm)
	Adapter weight	.10 lbs (.05 kg)



Technical Specifications - Graphics

HP DisplayPort to VGA	Connectors	DisplayPort and VGA connector
Adapter	Adapter length	8 in (20 cm)
	Adapter weight	.1 lbs (.06 kg)
	Maximum vertical refresh rate	85 Hz
	Display support	162 MHz RAMDAC
	Display max resolution	1600x1200

HP DisplayPort to VGA adapter display resolutions and refresh rates

NOTE: Other resolutions may be available but are not recommended as they may not have been tested and gualified by HP. Using the HP DisplayPort to VGA Adapter may require an update to the graphics driver installed on your system. To install the most up-to-date graphics driver go to: www.hp.com.

Resolution	Max refresh rate
640x480	85
800x600	85
1024x768	85
1280x720	85
1280x1024	85
1440x900	75
1600x1200	60
1680x1050	60
1920x1080	60-R
1920x1200	60-R

NOTE: 60-R denotes reduced blanking timings are used. Not all monitors support reduced blanking timing.



Technical Specifications - Internal Storage

7200 RPM Serial ATA	500-GB	Capacity	500,107,862,016 bytes	
Hard Drives		Height	1 in (2.54 cm)	
			Media diameter: 3.5 in (8.89 cm) Physical size: 4 in (10.2 cm)	
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	16 MB	
		Seek Time (typical	Single Track	2.0 ms
		reads, includes controller	Average	11 ms
		overhead, including settling)	Full-Stroke	21 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	976,773,168	
		Operating Temperature	e 41° to 131° F (5° to 55° (C)
	320-GB	Capacity	320,072,933,376 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.5 in (8 Physical size: 4 in (10.2	
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	8 MB	
		Seek Time (typical	Single Track	1.0 ms
		reads, includes controller	Average	8.5 ms
		settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	625,142,448	
		Operating Temperature	e41° to 131° F (5° to 55° (C)
	250-GB	Capacity	250,059,350,016 bytes	
		Height	1 in (2.54 cm)	
		Width	Media diameter: 3.5 in (8 Physical size: 4 in (10.2	,
		Interface	Serial ATA (3.0 Gb/s)	
		Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
		Buffer	8 MB	
		Seek Time (typical	Single Track	1.0 ms
		reads, includes controller	Average	8.5 ms
		overhead, including settling)	Full-Stroke	18 ms
		Rotational Speed	7,200 rpm	
		Logical Blocks	488,397,168	
		Operating Temperature	e 41° to 131° F (5° to 55° (C)
	160-GB	Capacity	160,041,885,696 bytes	
		Height	1 in (2.54 cm)	



Technical Specifications - Internal Storage

	Width	Media diameter: 3.5 Physical size: 4 in (, ,
	Interface	Serial ATA (3.0 Gb/s	s)
	Synchronous Transfer Rate (Maximum)	Up to 3 Gb/s	
	Buffer	8 MB	
	Seek Time (typical	Single Track	0.9 ms
	reads, includes controller	Average	9.3 ms
	overhead, including settling)	Full-Stroke	18 ms
	Rotational Speed	7,200 rpm	
	Logical Blocks	312,581,808	
	Operating Temperature	e41° to 131° F (5° to	55° C)
10,000 RPM Serial ATA 160-GB	Capacity	160,041,885,696 by	tes
Hard Drives	Height	1 in (2.54 cm)	
	Width	Media diameter: 2.5 in (? cm) Physical size: 4 in (10.2 cm)	
	Interface	Serial ATA (1.5 Gb/s	s), Native Command Queuing enabled
	Synchronous Transfer Rate (Maximum)	Up to 3.0 Gb/s	
	Cache	16 Mbytes	
	Seek Time (typical	Single Track	0.3 ms
	reads, includes controller	Average	4.6 ms
	overhead, including settling)	Full-Stroke	10.2 ms
	Rotational Speed	10,000 rpm	
	Logical Blocks	312,581,808	
	Operating Temperature	e41° to 131° F (5° to s	55° C)
80-GB	Capacity	80,026,361,856 byte	es
	Height	1 in (2.54 cm)	
	Width	Media diameter: 2.5 Physical size: 4 in (
	Interface	Serial ATA (1.5 Gb/s	s), Native Command Queuing enabled
	Synchronous Transfer Rate (Maximum)	Up to 3.0 Gb/s	
	Cache	16 Mbytes	
	Seek Time (typical	Single Track	0.3 ms
	reads, includes controller overhead, including	Average	4.6 ms
	settling)	Full-Stroke	10.2 ms
	Rotational Speed	10,000 rpm	
	-		
	Logical Blocks	156,301,488	



Technical Specifications - Internal Storage

64 GB Solid State Drive	e Capacity	64 GB	
	NAND Flash Memory	Multi Level Cell (MLC) wi	th wear leveling controller
	Interface type	SATA 3Gb/sec	
	Dimensions-external (W x H x D)	2.74 x 0.37 x 4 in (6.98 x	x 0.95 x 10.2 cm)
	Weight	0.14 lb (65 g)	
	Internal transfer rate	Write speed	Up to 220 MB/s
		Read speed	Up to 120 MB/s
	Host transfer rate	Ultra DMA mode	Up to 150 MB/s
	Power	DC power requirement	t 5 VDC 5%-100 mV ripple p-p
		Total power consumption	<1.12Watt
	Environmental	Temperature (operating) 32° to 158° F (0° to 70° C)
	(all conditions, non- condensing)	Relative Humidity (operating)	5% to 95%
		Maximum Wet Bulb Temperature (operating	84° F (29° C))
	Regulations		0, CISPR Pub 22 Class B, CNS 13438, Class B, R1113 and C1172 Class B

* For solid state disk drives, GB means 1 billion bytes. 16GB is the unformatted capacity of this drive before a portion of the drive is reserved for flash management features. Actual capacity varies by content and will be less than 15.8GB.



Technical Specifications - Input/Output Devices

USB Standard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Dimensions (L x W x H)	18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	+ 5VDC ± 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	USB Type A plug connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft® PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	e 50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidity	y 20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark	, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
	Ergonomic compliance	e ANSI HFS 100, ISO 9241	-4, and TUVGS
	Kit contents	Keyboard, installation gui	ide, warranty card, safety and comfort guide



PS/2 Standard	Physical	Keys	104, 105, 106, 107, 109 layout (depending
Keyboard	characteristics		upon country)
		Dimensions (L x W x H) 18.0 x 6.4 x 0.98 in (45.8 x 16.3 x 2.5 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	+ 5VDC ± 5%
		Power consumption	50-mA maximum (with three LEDs ON)
		System interface	PS/2 6-pin mini din connector
		ESD	CE level 4, 15-kV air discharge
		EMI - RFI	Conforms to FCC rules for a Class B computing device
		Microsoft PC 99 - 2001	Functionally compliant
	Mechanical	Languages	38 available
		Keycaps	Low-profile design
		Switch actuation	55-g nominal peak force with tactile feedback
		Switch life	20 million keystrokes (using Hasco modified tester)
		Switch type	Contamination-resistant switch membrane
		Key-leveling mechanisms	For all double-wide and greater-length keys
		Cable length	6 ft (1.8 m)
		Microsoft PC 99 - 2001	Mechanically compliant
		Acoustics	43-dBA maximum sound pressure level
	Environmental	Operating temperature	e 50° to 122° F (10° to 50° C)
		Non-operating temperature	-22° to 140° F (-30° to 60° C)
		Operating humidity	10% to 90% (non-condensing at ambient)
		Non-operating humidit	ty20% to 80% (non-condensing at ambient)
		Operating shock	40 g, six surfaces
		Non-operating shock	80 g, six surfaces
		Operating vibration	2-g peak acceleration
		Non-operating vibration	4-g peak acceleration
		Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
		Drop (in box)	42 in (107 cm) on concrete, 16-drop sequence
	Approvals	UL, CSA, FCC, CE Mark	<, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC
	Ergonomic complia	nce ANSI HFS 100, ISO 924	1-4, and TUVGS
HP USB Smartcard Keyboard	Physical characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
		Form factor	USB basic Smart Card keyboard
		Colors	Carbonite/Silver
		Dimensions (H x W x D	9) 18.2 x 6.3 x 1.3 in (46.3 x 16.1 x 3.3 cm)
		Weight	2 lb (0.9 kg) minimum

Technical Specifications - Innut/Output Devices

Keyboard	characteristics	neys	upon country)
		Form factor	USB basic Smart Card keyboard
		Colors	Carbonite/Silver
		Dimensions (H x W x D) 18.2 x 6.3 x 1.3 in (46.3 x 16.1 x 3.3 cm)
		Weight	2 lb (0.9 kg) minimum
	Electrical	Operating voltage	+ 5VDC ± 5%
		Power consumption	100-mA maximum (with four LEDs ON)
		System interface	USB Type A plug connector
		ESD	CE level 4, 15-kV air discharge



Technical Specifications - Input/Output Devices

	EMI - RFI	Conforms to FCC rules computing device	s for a Class B
	Microsoft PC 99 - 2001	Functionally compliant	t
Mechanical	Languages	30+ available	
	Keycaps	Low-profile design	
	Switch actuation		ce with tactile feedback
	Switch life		(using Hasco modified
	Switch type	Contamination-resista	nt membrane
	Key-leveling	For all double-wide an	d greater-length keys
	mechanisms		
	Cable length	6 ft (1.8 m)	
	Microsoft PC 99 - 2001	Mechanically complian	nt
	Acoustics	43-dBA maximum sou	nd pressure level
Environmental	Operating temperature	9 50° to 122° F (10° to 5	60° C)
	Non-operating temperature	-22° to 140° F (-30° to	60° C)
	Operating humidity	10% to 90% (non-cond	densing at ambient)
	Non-operating humidit	y 20% to 80% (non-cond	densing at ambient)
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration	2-g peak acceleration	
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box)	26 in (66 cm) on carpe	et, six-drop sequence
	Drop (in box)	42 in (107 cm) on cond sequence	crete, 16-drop
SMARTCARD function	Support	All ISO 7816 smart ca	rds
	Interface	Reads from and writes 4 memory and microp (T=0, T=1)	s to all ISO7816-1, 2, 3, rocessor smart cards
	Chipset	SCM STCII	
	Standard APIs supported	PC/SC, EMV2000, SE	T
	Power	USB Port	
		Short circuit detection and reader) Power supply complian EMV (5V, 60 mA) Supports 3-V and 5-V	nt with ISO7816 and
	Power consumption	250-mA maximum dra	
		keyboard with three LE	
	Communication	From card	Programmable from
	Communication		9,600 baud to 115,200 baud
		From computer	Up to 38,400 baud
	Landing mechanism	Contact device	Friction contact
		Card insertions rating	Up to 100,000 insertion cycles



Technical Specifications - Input/Output Devices Interface modes USB communications through USB port SCM protocol Automatic card insertion/removal detection **Reader performance USB** connection interface **Electro-magnetic** Europe 89/336/CEE guideline standards USA **USAFCC part 15** HP USB 2-Button Laser Scroll Wheel 24 Mouse **Maximum Rotation** 48 rats/sec Speed Switch Type wheel Switch Life Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times **Environmental Operating Temperature**32° to 104° F (0° to 40° C) -4° to 140° F (-20° to 60° C) Non-operating Temperature **Operating Humidity** 10% to 90% (non-condensing at ambient) Non-operating 20% to 80% (non-condensing at ambient) Humidity **Operating Shock** 40 g, six surfaces Non-operating Shock 80 g, six surfaces **Operating Vibration** 2-g peak acceleration Non-operating 4-g peak acceleration Vibration Electrical **Operating Voltage** + 5VDC ± 5% **Power Consumption MTBF** > 150,000 hrs ESD IEC-61000-4-2 criteria B, Contact discharge: +/- 4kV, Air discharge: +/- 8kV **EMI-RFI** FCC Class B **PC98** PC 99 Compliant Mechanical Resolution 800dpi 25 cm/sec **Tracking Speed** Acceleration 0.5mm **Switch Actuation** 0.6N (60gf) Switch Life Button - 3,000,000 Wheel - 1,000,000 times Tilt switch - 500,000 times 1850mm Cable Length PC98-99 PC99 compliant UL60950-1, UL 94, UL 746 (A-E), UL 796 **Regulatory Approvals** TUV/GS: EN 60950-1, EN 60825-1 FCC Class B, UL 1950, cUL, TUV GS, CE, C-tick, VCCI, BSMI, RRL



Technical Specificat	tions - Input/Output	Devices	
HP PS/2 Optical Scroll	Dimensions (H x L x W)	3.95 x 6.21 x 11.7 cm (1	.56 x 2.44 x 4.61 in)
Mouse	Weight	4.44 oz (126 g)	
	Environmental	Operating temperature	9 -32° to 104°F (0° to 40° C)
		Non-operating temperature	-4° to 140°F (-20° to 60° C)
		Operating humidity	10% to 90% (non condensing at ambient)
		Non-operating humidit	y 10% to 90% non condensing
		Operating shock	40 g, 6 surfaces
		Non-operating shock	80 g, 6 surfaces
		Operating vibration	2 g peak acceleration
		Non-operating vibration	4 g peak acceleration
		Drop (out of box)	80 cm height onto asphalt tile over concrete or equivalent, 5-drop in 5 direction except the cable face
	Electrical	Operating voltage	5 VDC ± 10%
		Power consumption	100mA
		System consumption	PS/2 mini-din connector
		ESD	CE level 4, 15 kV air discharge
		EMI-RFI	Conforms to FCC rules for a Class B computing device
		Microsoft PC99 - 2001	Functionally compliant
	Mechanical	Resolution	400 ± 20% DPI
		Tracking speed	10 in/s (25.4 cm/s) maximum
		Acceleration	100 in/s/s (2.54 m/s/s)
		Switch actuation	61 g nominal peak force
		Switch life	3,000,000 operations (using Hasco modified tester)
		Switch type	Low force micro-switches
		Tracking mechanism life	155 mi (250 km) at average speed of 10 in/s
		Cable length	6 ft (1.8 m)
		Microsoft PC99 - 2001	Mechanically compliant
	Scroll wheel	Width	8 mm
		Diameter	1.01 in (25.6 mm)
		Maximum rotation speed	48 rats/sec
		Switch type	Light force micro-switch
		Switch life	1 million operations
		Mechanical life	Minimum 200,000 revolutions
	Regulatory approvals	Compliant	UL, CSA, FCC, CE Mark, TUV, TUV GS, VCCI, BSMI, C-Tick, MIC

 HP USB Optical Scroll
 Dimensions (H x L x W)
 1.5 x 4.5 x 2.5 in (3.8 x 11.6 x 6.3 cm)

 Mouse
 Weight
 0.27 lb (0.12 kg)

 Cable length
 72.8 in (185 cm)



Technical Specifications - Optical Storage

HP SATA Blu-ray Write	erHeight	5.25-inch, half-height, t	tray-load	
-	Orientation	Either horizontal or ver	tical	
	Interface type	SATA/ATAPI		
	Disc capacity	50 GB DL or 25 GB sta	andard	
	Dimensions (W x H x D) 5.9 x 1.7 x 7.5 in (15.0) x 4.4 x 19.0 cm)	
	Weight (max)	2.0 lb (907g)		
			Single-layer	Double-layer
	Write speed	BD-R	2x, 4x CLV, 6x CAV	2x, 4x CLV
		BD-RE	2.3x	2x CLV
		DVD-R	2x, 4x CLV, 8x ZCLV, 8x, 12x PCAV, 16x CAV	2x, 4x CLV
		DVD-RW	1x, 2x, 4x, 6x CLV	Not supported
		DVD+R	2.4x, 4x CLV, 8x ZCLV 8x, 12x PCAV, 16x CAV	/, 2.4x, 4x CLV
		DVD+RW	2.4x, 4x, 6x CLV, 8x ZCLV	Not supported
		DVD-RAM	2x, 3x CLV, 3-5x PCA	V
		CD-R	8x,16x CLV, 24x, 32x I	PCAV, 40x CAV
		CD-RW	4x, 10x, 16x CLV, 24x	ZCLV
			Single-layer	Double-layer
	Read speeds	BD-ROM	6x CAV	4.8x CAV
		BD-R	6x CAV	4.8x CAV
		BD-RE (SL/DL)	4.8x CAV	4.8x CAV
		DVD-ROM	16x CAV	8x CAV
		DVD-R	12x CAV	8x CAV
		DVD-RW	10x CAV	Not support
		DVD+R	12x CAV	8x CAV
		DVD+RW	10x CAV	Not support
		BDMV (AACS Compliant Disc)	4.8x CAV	
		DVD-RAM	2x, 3x CLV, 3x-5x PCA	AV
		DVD-Video (CSS Compliant Disc)	8x CAV	
		CD-R/RW/ROM	40x / 40x / 40x CAV	
		CD-DA (DAE)	32x CAV	
		80 mm CD	16x CAV	
	Sustained Transfer rate	eBD-ROM	215.79 Mbits/s (6x) ma	IX.
		DVD-ROM	16.62 Mbytes/s (16x) r	nax.
		CD-ROM	6,000 KB/s (40x) max.	
	Burst Transfer rate		1.5Gbps bits/s (10b sid 1.2Gbps bits/s (8b side	
	Multimedia MPC-3 compliant		Yes	
	Access times	Random	DVD: < 140 ms (typica	l), CD: < 125 ms (typical)
	(typical reads, including setting)	Full Stroke	DVD: < 250 ms (seek),	, CD: < 210 ms (seek)



Technical Specifications - Optical Storage

	Power Environmental (all conditions non-condensing)	Source DC Power Requirement DC Current Temperature (operating) Relative Humidity (operating) Maximum Wet Bulb Temperature (operating)	SATA DC power receptacle 5 VDC ± 5%-100 mV ripple p-p 12 VDC ± 5%-200 mV ripple p-p 5 VDC -1000 mA typical, 1600 mA maximum 12 VDC -600 mA typical, 1400 mA maximum 41° to 122° F (5° to 50° C) 10% to 90% 86° F (30° C)
HP SATA SuperMulti LightScribe DVD Writer Drive	Interface type Disc capacity	5.25-inch, half-height, tr Either horizontal or vert SATA/ATAPI 8.5 GB DL or 4.7 GB st	andard
	Dimensions (W x H x D) Weight (max)	•	x 4.4 x 20.3 cm)
	Weight (max) Write speeds	2.6 lb (1.2 kg) DVD-RAM	Up to 12X
	Read speeds	DVD+R DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW DVD-RAM DVD+RW, DVD-RW, DVD+R DL, DVD-R DL DVD-ROM DL DVD-ROM, DVD+R, DVD-R	Up to 16X Up to 8X Up to 8X Up to 8X Up to 16X Up to 6X Up to 48X Up to 32X Up to 32X Up to 12X Up to 8X Up to 8X
		CD-ROM, CD-R CD-RW	Up to 48X
	Access time (typical reads, including	Random	Up to 32X DVD: < 140 ms (typical), CD: < 125 ms (typical)
	settling)	Full Stroke	DVD: < 250 ms (seek), CD: < 210 ms (seek)
	Power	Source	SATA DC power receptacle
		DC Power Requireme	ent5 VDC \pm 5%-100 mV ripple p-p
		DC Current	12 VDC ± 5%-200 mV ripple p-p 5 VDC (< 1000 mA typical, 1600 mA maximum) 12 VDC (< 600 mA typical, 1400 mA maximum)
	Environmental conditions (operating - non-condensing)	Temperature Relative Humidity Maximum Wet Bulb Temperature	41° to 122° F (5° to 50° C) 10% to 90% 86° F (30° C)



Technical Specifications - Optical Storage

SATA DVD-ROM Drive	Height	5.25-inch, half-height, tra	ay-load			
	Orientation	Either horizontal or vertical				
	Interface type	SATA/ATAPI				
	Disc capacity	Single layer: Up to 4.7 GB (6 times capacity of CD-ROM) Double layer: Up to 8.5 GB (12 times capacity of CD-ROM)				
	Dimensions (W x H x D) 5.9 x 1.7 x 8.0 in (15.0 x 4.4 x 20.3 cm)					
	Weight (max)	2.6 lb (1.2 kg)				
	Read speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL	Up to 8X			
		DVD-ROM	Up to 16X			
		DVD-RAM	Up to 4X			
		CD-ROM, CD-R	Up to 48X			
		CD-RW	Up to 32X			
	Removable Storage -	Media	Read	Write		
	Media Compatibility -	CD-ROM	Yes	No		
	DVD-ROM	CD-R	Yes	No		
		CD-RW	Yes	No		
		DVD-ROM	Yes	No		
		DVD-ROM DL	Yes	No		
		DVD-RAM	Yes	No		
		DVD+R	Yes	No		
		DVD+R DL	Yes	No		
		DVD+RW	Yes	No		
		DVD-R	Yes	No		
		DVD-RW	Yes	No		
		DVD-R DL	Yes	No		
	Access times (typical reads, including	Random	DVD: < 140 ms (tyį (typical)	bical), CD: < 125 ms		
	setting)	Full Stroke	DVD: < 250 ms (se	ek), CD: < 210 ms (seek)		
		Cache Buffer	2 MB (minimum)			
		Data Transfer Modes		6.7 MB/s); ATA Multi-word MB/s); ATA UltraDMA -default)		
	Power	Source	SATA DC power re	,		
		DC Power Requireme	nt5 VDC ± 5%-100 m 12 VDC ± 5%-200 r			
		DC Current	5 VDC - <1000 mA maximum	typical, < 1600 mA typical, < 1400 mA		
	Environmental	Temperature	41° to 122° F (5° to	50° C)		
	(all conditions	Relative Humidity	10% to 90%			
	non-condensing)	Maximum Wet Bulb Temperature	86° F (30° C)			



Technical Specifications - Removable Storage

HP 22-in-1 (with 1394)	USB Interface	USB 2.0 High-speed inte	rface
Media Card Reader		NOTE: Requires the USE port or a USB 2.0 PCI ca	B cable to be connected to the internal USB 2.0 ird.
	1394 Interface		al ports; 1 IEEE-1394a internal port (connects e on the media card reader)
	Advance protocol support	 Supports hardware Supports MS 4-bit Supports MS-PRO Supports MS PRO Supports SD 4-bit p Supports high-spee Supports high-spee 	ECC (Error Correction Code) function CRC (Cyclic Redundancy Check) function parallel transfer mode 4-bit parallel transfer mode -HG Duo 4-bit parallel transfer mode parallel transfer mode ed 50Mhz SD 4-bit card (version 2.0) ed 52Mhz MMC 8-bit card (version 4.2) with PIO mode 6 and Ultra DMA mode
	Supported media type	 MultiMediaCard 4.2 Reduced Size Multi Mobile HC) Secure Digital Cardinal Secure Digital High miniSD miniSD High Capa Micro SD (T-Flash) Micro SD HC Memory Stick Memory Stick Sele Memory Stick Duo Memory Stick PRC 	e II IMC) tiMediaCard (RS MMC) 2 (MMC Plus, including MMC Plus HC) tiMediaCard 4.2 (MMC Mobile, including MMC d (SD) n Capacity (SDHC) city) ect (MS Duo) D (MS PRO) D Duo (MS PRO Duo) D-HG Duo y Stick (MG)
	Supported media type with card adapter		ro (M2)
	Environmental	Operational Environmental Extremes	Test Parameters/Conditions - Power applied, unit operating on system $\pm 5\%$ nominal supply voltage. 10°C 10% R.H. ≥ 24 hours 10°C 90% R.H. ≥ 24 hours 20°C 90% R.H. ≥ 24 hours 30°C 90% R.H. ≥ 24 hours 40°C 90% R.H. ≥ 24 hours 50°C 90% R.H. ≥ 24 hours 50°C 10% R.H. ≥ 24 hours
		Storage Environmenta Extremes	I Test Parameters/Conditions 140°F (60°C) @ 80% R.H. for 96 hours -22°F (-30°C) @ 20% R.H. for 48 hours No power applied Delta °C < 1.0°C/min Delta % R.H. < 1.5% R.H./min



Technical Specifications - Removable Storage

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport Specification Rev. 1.0, Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3 FCC, CE, BSMI, C-Tick, VCCI, MIC, cUL, TUV-T



Technical Specifications - Environmental Data

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Microtower			
Eco-Label Certifications and declarations	be labeled with one or more of t	n the process of being certified to hese marks:	the following approvals and may
	 US Energy Star IT ECO declaration EPEAT – Gold 		
System Configuration	The configuration used for the E Microtower model is based on a	nergy Consumption and Declared typically configured product.	Noise Emissions data for the
Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	31.3720 W	32.1179 W	31.8169 W
Sleep (Energy Star low power mode)	2.4746 W	2.6361 W	2.4347 W
Off	0.7153 W	0.8560 W	0.6980 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	107 BTU/hr	110 BTU/hr	109 BTU/hr
Sleep	8 BTU/hr	9 BTU/hr	8 BTU/hr
Off	2 BTU/hr	3 BTU/hr	2 BTU/hr
* Heat dissipation is calc	culated based on the measured wa	atts, assuming the service level is	attained for one hour.
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Cound Deposition	
System Fan Off	Sound Power (LWAd, bels)	Sound Pressure (LpAm, decibels)	
Idle	3.8	27	
	0.0	_ ;	
Fixed Disk (random writes)	3.8	28	
•		28 mply with EU Directive 2006/66/E	C
writes)		mply with EU Directive 2006/66/E	C
writes)	This battery(s) in this product co	mply with EU Directive 2006/66/E not contain: by weight	C
writes)	This battery(s) in this product co Batteries used in the product do Mercury greater the 5ppm	omply with EU Directive 2006/66/E not contain: by weight opm by weight	C
writes)	This battery(s) in this product co Batteries used in the product do • Mercury greater the 5ppm • Cadmium greater than 10 Battery size: CR2032 (coin cell) Battery type: Li Ion • This product is in complia	omply with EU Directive 2006/66/E not contain: by weight opm by weight	
writes) Batteries	 This battery(s) in this product constrained by the product do a strained by the product do a strained by the product of the product is in compliand directive - 2002/95/EC. This HP product is design 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elect	dous Substances (RoHS)
writes) Batteries	 This battery(s) in this product constrained by the product do an encoded by the product do an encoded by the product of the product is in compliand directive - 2002/95/EC. This HP product is design (WEEE) Directive - 2002/ 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elect	dous Substances (RoHS) trical and Electronic Equipment
writes) Batteries	 This battery(s) in this product constrained by the product do the product do the product do the product greater than 10 and the product greater than 10 and the product greater than 10 and the product is product is a product is a product is a product is a product is design (WEEE) Directive – 2002/ This product is in compliant prinking Water and Toxic 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elec 96/EC. nce with California Proposition 65 Enforcement Act of 1986).	dous Substances (RoHS) trical and Electronic Equipment (State of California; Safe
writes) Batteries	 This battery(s) in this product constrained by the product do a state of the product do a state of the product is in complianed to the product is in complianed to the product is in complianed to the product of the product is in complianed to the product of the produc	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elec 96/EC. nce with California Proposition 65	dous Substances (RoHS) trical and Electronic Equipment (State of California; Safe
writes) Batteries	 This battery(s) in this product constant of the product do a state of the product do a state of the product is in compliant directive - 2002/95/EC. This HP product is in compliant directive - 2002/ This product is in compliant Drinking Water and Toxic This product is in compliant Drinking Water and Toxic This product is in compliant directive is in compliant Drinking Water and Toxic 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elec 96/EC. nce with California Proposition 65 Enforcement Act of 1986).	dous Substances (RoHS) trical and Electronic Equipment (State of California; Safe standard at the Gold level, see
writes) Batteries	 This battery(s) in this product constrained by the product do an encoded by the product do an encoded by the product of the product of the product of the product of the product is the product is in compliand directive - 2002/95/EC. This Product is in compliand directive - 2002/95/EC. This product is in compliand prinking Water and Toxic This product is in compliand the product is in compliand prinking Water and Toxic This product is in compliand the product is in compliand prinking water and Toxic Plastics parts weighing over 1501043. 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elect 96/EC. nce with California Proposition 65 Enforcement Act of 1986). nce with the IEEE 1680 (EPEAT) er 25 grams used in the product a	dous Substances (RoHS) trical and Electronic Equipment (State of California; Safe standard at the Gold level, see re marked per ISO 11469 and
writes) Batteries	 This battery(s) in this product constrained by the product do the product do the product do the product greater the product do the constrained by the product is product is in compliant directive - 2002/95/EC. This product containt directive - 2002/95/EC. 	omply with EU Directive 2006/66/E o not contain: by weight opm by weight nce with the Restrictions of Hazar ed to comply with the Waste Elect 96/EC. nce with California Proposition 65 Enforcement Act of 1986). nce with the IEEE 1680 (EPEAT)	dous Substances (RoHS) trical and Electronic Equipment (State of California; Safe standard at the Gold level, see re marked per ISO 11469 and by wt.)



Technical Specifications - Environmental Data

	Packaging Materials	External	
		Corrugated Paper	1835 g
		Internal	
		Polyethylene low density solid	150 g
		Polyethylene low density foam	20 g
	 The Polyethylene 		I is made from 100% recycled content. I is made from 100% recycled content. 0% recycled content.
Small Form Factor			
Eco-Label Certifications & declarations	be labeled with one or m		ed to the following approvals and may
	 US Energy Star IT ECO declaration EPEAT – Silver 	n	
System Configuration	5	for the Energy Consumption and Dec el is based on a typically configured	
Energy Consumption	115 VAC	230 VAC	100 VAC
Normal Operation	27.4159 W	27.1680 W	27.7080 W
Sleep (Energy Star low power mode)	2.5527 W	2.7644 W	2.5316 W
Off	0.7149 W	0.8667 W	0.7003 W
Heat Dissipation*	115 VAC	230 VAC	100 VAC
Normal Operation	94 BTU/hr	93 BTU/hr	95 BTU/hr
Sleep	9 BTU/hr	9 BTU/hr	9 BTU/hr
Off	2 BTU/hr	3 BTU/hr	2 BTU/hr
* Heat dissipation is calc	ulated based on the mea	sured watts, assuming the service le	vel is attained for one hour.

* Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise

Emissions (in accordance with ISO 7779 and ISO 9296)

System Fan Off	Sound Power (LWAd, bels)	Sound Pressure (LpAm, decibels)
Idle	3.8	27
Fixed Disk (random writes)	3.9	28



Technical Specifications - Environmental Data

Batteries This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater the 5ppm by weight
- Cadmium greater than 10ppm by weight

Battery size: CR2032 (coin cell) Battery type: Li Ion

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2002/95/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Silver level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.
- This product contains 0% post consumer recycled plastic (by wt.)
- This product is 95.1% recyclable when properly disposed of at end of life.

Packaging Materials External

Corrugated Carton	1705 g
Internal	
EPE-Expanded Polyethylene	198 g
Polyethylene low density foam	39 g

- The EPE-Expanded Polyethylene packaging material is made from 100% recycled content.
- The Polyethylene low density foam packaging material is made from 100% recycled content.
- The Corrugated Carton packaging materials contains at least 75% recycled content.

Small Form Factor and Microtower

email i emi i aeter	
RoHS Compliance	Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations, including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis. By July 1, 2006, RoHS substances will be virtually eliminated (virtually = to levels below legal limits) for all HP electronic products subject to the RoHS Directive, except where it is widely recognized that there is no technically feasible alternative (as indicated by an exemption under the EU RoHS Directive).
Material Usage	 This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries
	 Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs)

Polybrominated Biphenyl Ethers (PBBEs)



Technical Specific	ations - Environmental Data
	 Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging	HP follows these guidelines to decrease the environmental impact of product packaging:
End-of-life Management and Recycling	 Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
Hewlett-Packard Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html

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